



RF Power GaN Transistor

This 34 W asymmetrical Doherty RF power GaN transistor is designed for cellular base station applications requiring very wide instantaneous bandwidth capability covering the frequency range of 2496 to 2690 MHz.

This part is characterized and performance is guaranteed for applications operating in the 2496 to 2690 MHz band. There is no guarantee of performance when this part is used in applications designed outside of these frequencies.

2600 MHz

- Typical Doherty Single-Carrier W-CDMA Performance: $V_{DD} = 48$ Vdc, $I_{DQA} = 120$ mA, $V_{GSB} = -5.3$ Vdc, $P_{out} = 34$ W Avg., Input Signal PAR = 9.9 dB @ 0.01% Probability on CCDF.

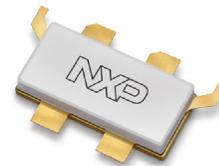
Frequency	G_{ps} (dB)	η_D (%)	Output PAR (dB)	ACPR (dBc)
2496 MHz	14.7	54.2	8.1	-29.3
2590 MHz	14.8	55.5	7.9	-30.9
2690 MHz	14.2	54.0	7.8	-34.1

Features

- High terminal impedances for optimal broadband performance
- Advanced high performance in-package Doherty
- Able to withstand extremely high output VSWR and broadband operating conditions

A3G26H200W17S

2496–2690 MHz, 34 W Avg., 48 V
AIRFAST RF POWER GaN
TRANSISTOR



NI-780S-4S2S

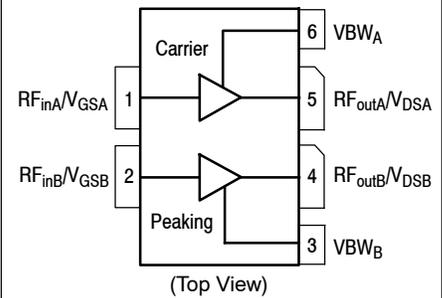


Figure 1. Pin Connections



Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	125	Vdc
Gate-Source Voltage	V_{GS}	-8, 0	Vdc
Operating Voltage	V_{DD}	0 to +55	Vdc
Maximum Forward Gate Current, I_G (A+B), @ $T_C = 25^\circ\text{C}$	I_{GMAX}	29	mA
Storage Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$
Case Operating Temperature Range	T_C	-55 to +150	$^\circ\text{C}$
Operating Active Die Surface Temperature Range	T_J	-55 to +225	$^\circ\text{C}$
Maximum Channel Temperature (1)	T_{CH}	275	$^\circ\text{C}$

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance by Infrared Measurement, Active Die Surface-to-Case Case Temperature 77°C , $P_D = 31.8\text{ W}$	$R_{\theta JC}$ (IR)	1.2 (2)	$^\circ\text{C}/\text{W}$
Thermal Resistance by Finite Element Analysis, Channel-to-Case Case Temperature 90°C , $P_D = 31.8\text{ W}$	$R_{\theta CHC}$ (FEA)	1.75 (3)	$^\circ\text{C}/\text{W}$

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JS-001-2017)	1C
Charge Device Model (per JS-002-2014)	C3

Table 4. Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
----------------	--------	-----	-----	-----	------

Off Characteristics (4)

Drain-Source Breakdown Voltage ($V_{GS} = -8\text{ Vdc}$, $I_D = 16.2\text{ mAdc}$) ($V_{GS} = -8\text{ Vdc}$, $I_D = 29.7\text{ mAdc}$)	$V_{(BR)DSS}$	150 150	—	—	Vdc
--	---------------	------------	---	---	-----

On Characteristics — Side A, Carrier

Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 10\text{ mAdc}$)	$V_{GS(th)}$	-3.5	-3	-2.5	Vdc
Gate Quiescent Voltage ($V_{DD} = 48\text{ Vdc}$, $I_{DA} = 120\text{ mAdc}$, Measured in Functional Test)	$V_{GSA(Q)}$	-3.2	-2.7	-2.2	Vdc
Gate-Source Leakage Current ($V_{DS} = 150\text{ Vdc}$, $V_{GS} = -8\text{ Vdc}$)	I_{GSS}	-5.0	—	—	mAdc

On Characteristics — Side B, Peaking

Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 18.9\text{ mAdc}$)	$V_{GS(th)}$	-4.0	-3	-2.5	Vdc
Gate-Source Leakage Current ($V_{DS} = 150\text{ Vdc}$, $V_{GS} = -8\text{ Vdc}$)	I_{GSS}	-4.75	—	—	mAdc

1. Reliability tests were conducted at 225°C . Operations with T_{CH} at 275°C will reduce median time to failure.
2. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.nxp.com/RF> and search for AN1955.
3. $R_{\theta CHC}$ (FEA) must be used for purposes related to reliability and limitations on maximum channel temperature. MTTF may be estimated by the expression $MTTF$ (hours) = $10^{[A + B/(T + 273)]}$, where T is the channel temperature in degrees Celsius, $A = -11.1$ and $B = 8366$.
4. Each side of device measured separately.

(continued)

Table 4. Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
Functional Tests ⁽¹⁾ (In NXP Doherty Production Test Fixture, 50 ohm system) $V_{DD} = 48\text{ Vdc}$, $I_{DQA} = 120\text{ mA}$, $V_{GSB} = -5.3\text{ Vdc}$, $P_{out} = 34\text{ W Avg.}$, $f = 2690\text{ MHz}$, Single-Carrier W-CDMA, IQ Magnitude Clipping, Input Signal PAR = 9.9 dB @ 0.01% Probability on CCDF. ACPR measured in 3.84 MHz Channel Bandwidth @ $\pm 5\text{ MHz}$ Offset. [See note on correct biasing sequence.]					
Power Gain	G_{ps}	13.0	14.2	16.0	dB
Drain Efficiency	η_D	46.0	54.0	—	%
P_{out} @ 3 dB Compression Point, CW	P3dB	51.9	52.5	—	dBm
Adjacent Channel Power Ratio	ACPR	—	-34.1	-27.0	dBc

Wideband Ruggedness (In NXP Doherty Production Test Fixture, 50 ohm system) $I_{DQA} = 120\text{ mA}$, $V_{GSB} = -5.3\text{ Vdc}$, $f = 2590\text{ MHz}$, Additive White Gaussian Noise (AWGN) with 10 dB PAR

ISBW of 400 MHz at 55 Vdc, 120 W Avg. Modulated Output Power (7 dB Input Overdrive from 34 W Avg. Modulated Output Power)	No Device Degradation
---	-----------------------

Typical Performance (In NXP Doherty Production Test Fixture, 50 ohm system) $V_{DD} = 48\text{ Vdc}$, $I_{DQA} = 120\text{ mA}$, $V_{GSB} = -5.3\text{ Vdc}$, 2496–2690 MHz Bandwidth

P_{out} @ 3 dB Compression Point ⁽²⁾	P3dB	—	178	—	W
AM/PM (Maximum value measured at the P3dB compression point across the 2496–2690 MHz bandwidth)	Φ	—	-26	—	°
VBW Resonance Point (IMD Third Order Intermodulation Inflection Point)	VBW_{res}	—	240	—	MHz
Gain Flatness in 194 MHz Bandwidth @ $P_{out} = 34\text{ W Avg.}$	G_F	—	0.7	—	dB
Gain Variation over Temperature (-40°C to +85°C)	ΔG	—	0.015	—	dB/°C
Output Power Variation over Temperature (-40°C to +85°C)	ΔP_{1dB}	—	0.001	—	dB/°C

Table 5. Ordering Information

Device	Tape and Reel Information	Package
A3G26H200W17SR3	R3 Suffix = 250 Units, 44 mm Tape Width, 13-inch Reel	NI-780S-4S2S

1. Part internally matched both on input and output.
2. P3dB = $P_{avg} + 7.0\text{ dB}$ where P_{avg} is the average output power measured using an unclipped W-CDMA single-carrier input signal where output PAR is compressed to 7.0 dB @ 0.01% probability on CCDF.

NOTE: Correct Biasing Sequence for GaN Depletion Mode Transistors**Turning the device ON**

1. Set V_{GS} to -5 V
2. Turn on V_{DS} to nominal supply voltage (48 V)
3. Increase V_{GS} until I_{DS} current is attained
4. Apply RF input power to desired level

Turning the device OFF

1. Turn RF power off
2. Reduce V_{GS} down to -5 V
3. Reduce V_{DS} down to 0 V (Adequate time must be allowed for V_{DS} to reduce to 0 V to prevent severe damage to device.)
4. Turn off V_{GS}

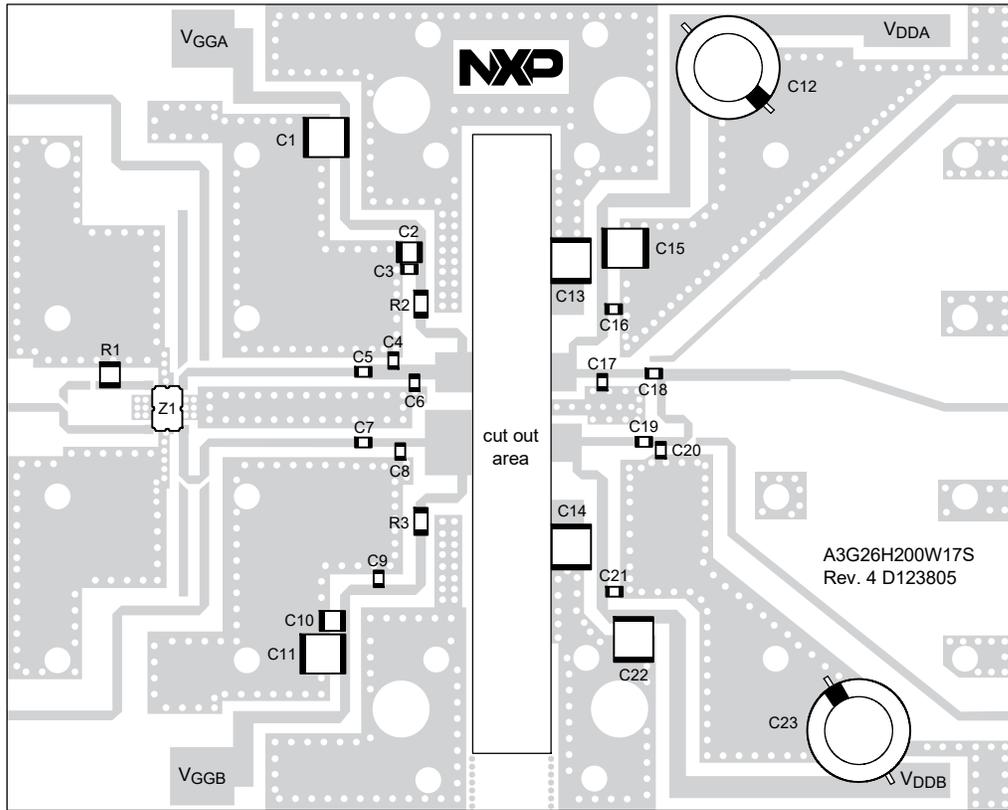
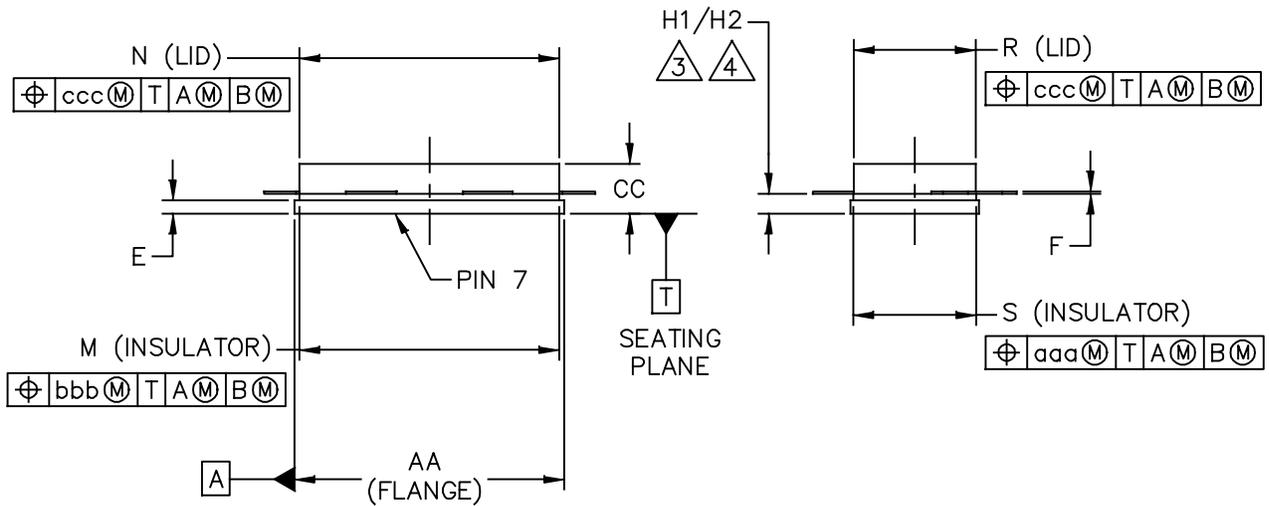
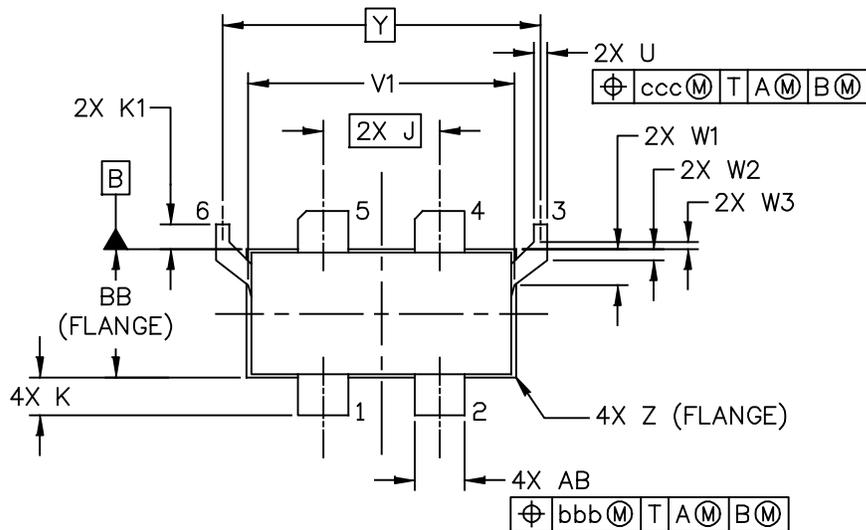


Figure 2. A3G26H200W17S Production Test Circuit Component Layout

Table 6. A3G26H200W17S Production Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
C1, C11, C13, C14, C15, C22	10 μ F Chip Capacitor	C5750X7S2A106M230KB	TDK
C2, C10	1 μ F Chip Capacitor	C3225JB2A105K200AA	TDK
C3, C5, C7, C9, C16, C21	8.2 pF Chip Capacitor	600F8R2BT250XT	ATC
C4, C6	0.5 pF Chip Capacitor	600F0R5BT250XT	ATC
C8, C17	0.3 pF Chip Capacitor	600F0R3BT250XT	ATC
C12, C23	470 μ F, 100 V Electrolytic Capacitor	MCGPR100V477M16X32	Multicomp
C18	2.4 pF Chip Capacitor	600F2R4BT250XT	ATC
C19	3.6 pF Chip Capacitor	600F3R6BT250XT	ATC
C20	0.2 pF Chip Capacitor	600F0R2BT250XT	ATC
R1	50 Ω , 10 W Termination Chip Resistor	C10A50Z4	Anaren
R2, R3	3 Ω , 1/4 W Chip Resistor	CRCW12063R00JNEA	Vishay
Z1	2300–2700 MHz Band, 90°, 2 dB Hybrid Coupler	X3C25P1-02S	Anaren
PCB	Rogers RO4350B, 0.020", $\epsilon_r = 3.66$	D123805	MTL

PACKAGE DIMENSIONS



© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE						
TITLE: <div style="text-align: center; font-size: 1.2em;">NI-780S-4S2S</div>	<table style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 60%;">DOCUMENT NO: 98ASA01208D</td> <td style="width: 40%;">REV: 0</td> </tr> <tr> <td colspan="2">STANDARD: NON-JEDEC</td> </tr> <tr> <td>SOT1799-6</td> <td style="text-align: right;">14 AUG 2018</td> </tr> </table>		DOCUMENT NO: 98ASA01208D	REV: 0	STANDARD: NON-JEDEC		SOT1799-6	14 AUG 2018
DOCUMENT NO: 98ASA01208D	REV: 0							
STANDARD: NON-JEDEC								
SOT1799-6	14 AUG 2018							

NOTES:

1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS H1 AND H2 ARE MEASURED .030 INCH (0.762 MM) AWAY FROM FLANGE PARALLEL TO DATUM B TO CLEAR EPOXY FLOW OUT. H1 APPLIES TO PINS 1, 2, 4 & 5. H2 APPLIES TO PINS 3 & 6.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.805	.815	20.45	20.70	R	.365	.375	9.27	9.53
BB	.380	.390	9.65	9.91	S	.365	.375	9.27	9.53
CC	.125	.170	3.18	4.32	U	.035	.045	0.89	1.14
E	.035	.045	0.89	1.14	V1	.795	.805	20.19	20.45
F	.004	.007	0.10	0.18	W1	.0975	.1175	2.48	2.98
H1	.057	.067	1.45	1.70	W2	.0225	.0425	0.57	1.08
H2	.054	.070	1.37	1.78	W3	.0125	.0325	0.32	0.83
J	.350 BSC		8.89 BSC		Y	.956 BSC		24.28 BSC	
K	.0995	.1295	2.53	3.29	Z	R.000	R.040	R0.00	R1.02
K1	.070	.090	1.78	2.29	AB	.145	.155	3.68	3.94
M	.774	.786	19.66	19.96	aaa	.005		0.13	
N	.772	.788	19.61	20.02	bbb	.010		0.25	
					ccc	.015		0.38	

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE: NI-780S-4S2S			DOCUMENT NO: 98ASA01208D REV: 0		
			STANDARD: NON-JEDEC		
			SOT1799-6		14 AUG 2018

PRODUCT DOCUMENTATION, SOFTWARE AND TOOLS

Refer to the following resources to aid your design process.

Application Notes

- AN1908: Solder Reflow Attach Method for High Power RF Devices in Air Cavity Packages
- AN1955: Thermal Measurement Methodology of RF Power Amplifiers

Software

- .s2p File

Development Tools

- Printed Circuit Boards

REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	Mar. 2020	<ul style="list-style-type: none">• Initial release of data sheet

How to Reach Us:

Home Page:
nxp.com

Web Support:
nxp.com/support

Information in this document is provided solely to enable system and software implementers to use NXP products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits based on the information in this document. NXP reserves the right to make changes without further notice to any products herein.

NXP makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does NXP assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in NXP data sheets and/or specifications can and do vary in different applications, and actual performance may vary over time. All operating parameters, including "typicals," must be validated for each customer application by customer's technical experts. NXP does not convey any license under its patent rights nor the rights of others. NXP sells products pursuant to standard terms and conditions of sale, which can be found at the following address: nxp.com/SalesTermsandConditions.

NXP, the NXP logo and Airfast are trademarks of NXP B.V. All other product or service names are the property of their respective owners.

© 2020 NXP B.V.